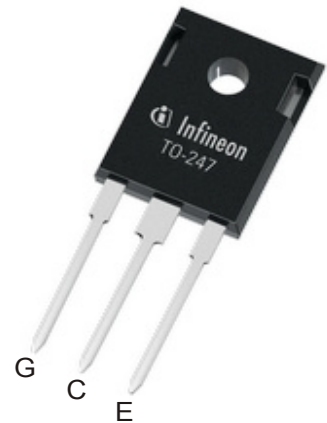
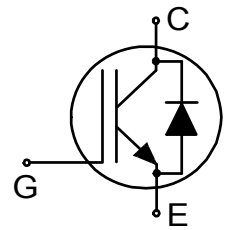


Resonant Switching Series

Reverse conducting IGBT with monolithic body diode

Features:

- Offers new higher breakdown voltage to 1350V for improved reliability
- Powerful monolithic body diode with low forward voltage designed for soft commutation only
- TRENCHSTOP™ technology offering:
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
 - low V_{CEsat}
 - easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Low EMI
- Qualified according to JESD-022 for target applications
- Pb-free lead plating; RoHS compliant
- Halogen free (according to IEC 61249-2-21)
- Complete product spectrum and PSpice Models:
<http://www.infineon.com/igbt/>

**Applications:**

- Inductive cooking
- Inverterized microwave ovens
- Resonant converters
- Soft switching applications

Package pin definition:

- Pin 1 - gate
- Pin 2 & backside - collector
- Pin 3 - emitter

**Key Performance and Package Parameters**

| Type | V_{CE} | I_C | $V_{CEsat}, T_{vj}=25^{\circ}C$ | T_{vjmax} | Marking | Package |
|-------------|----------|-------|---------------------------------|-------------|----------|------------|
| IHW20N135R3 | 1350V | 20A | 1.6V | 175°C | H20R1353 | PG-TO247-3 |

Table of Contents

| | |
|---|----|
| Description | 1 |
| Table of Contents | 2 |
| Maximum Ratings | 3 |
| Thermal Resistance | 3 |
| Electrical Characteristics | 4 |
| Electrical Characteristics Diagrams | 6 |
| Package Drawing | 12 |
| Testing Conditions | 13 |
| Revision History | 14 |
| Disclaimer | 15 |

Resonant Switching Series

Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

| Parameter | Symbol | Value | Unit |
|--|-------------|----------------------|------------------|
| Collector-emitter voltage | V_{CE} | 1350 | V |
| DC collector current, limited by T_{vjmax} $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$ | I_C | 40.0 20.0 | A |
| Pulsed collector current, t_p limited by T_{vjmax} | I_{Cpuls} | 60.0 | A |
| Turn off safe operating area $V_{CE} \leq 1350\text{V}$, $T_{vj} \leq 175^\circ\text{C}$ | - | 60.0 | A |
| Diode forward current, limited by T_{vjmax} $T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$ | I_F | 40.0 20.0 | A |
| Diode pulsed current, t_p limited by T_{vjmax} | I_{Fpuls} | 60.0 | A |
| Gate-emitter voltage Transient Gate-emitter voltage ($t_p \leq 10\mu\text{s}$, $D < 0.010$) | V_{GE} | ± 20 ± 25 | V |
| Power dissipation $T_c = 25^\circ\text{C}$ Power dissipation $T_c = 100^\circ\text{C}$ | P_{tot} | 310.0 155.0 | W |
| Operating junction temperature | T_{vj} | -40...+175 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55...+175 | $^\circ\text{C}$ |
| Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s | | 260 | $^\circ\text{C}$ |
| Mounting torque, M3 screw Maximum of mounting processes: 3 | M | 0.6 | Nm |

Thermal Resistance

| Parameter | Symbol | Conditions | Value | | | Unit |
|--|---------------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |
| R_{th} Characteristics | | | | | | |
| IGBT thermal resistance, junction - case | $R_{th(j-c)}$ | | - | - | 0.48 | K/W |
| Diode thermal resistance, junction - case | $R_{th(j-c)}$ | | - | - | 0.48 | K/W |
| Thermal resistance junction - ambient | $R_{th(j-a)}$ | | - | - | 40 | K/W |

Resonant Switching Series

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|--------------------------------------|---------------|--|-------|------|------|---------------|
| | | | min. | typ. | max. | |
| Static Characteristic | | | | | | |
| Collector-emitter breakdown voltage | $V_{(BR)CES}$ | $V_{GE} = 0\text{V}, I_C = 0.50\text{mA}$ | 1350 | - | - | V |
| Collector-emitter saturation voltage | V_{CESat} | $V_{GE} = 15.0\text{V}, I_C = 20.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - | 1.60 | 1.80 | V |
| | | | - | 1.80 | - | |
| | | | - | 1.90 | - | |
| Diode forward voltage | V_F | $V_{GE} = 0\text{V}, I_F = 20.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - | 1.60 | 1.80 | V |
| | | | - | 1.73 | - | |
| | | | - | 1.80 | - | |
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $I_C = 0.50\text{mA}, V_{CE} = V_{GE}$ | 5.1 | 5.8 | 6.4 | V |
| Zero gate voltage collector current | I_{CES} | $V_{CE} = 1350\text{V}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - | - | 100 | μA |
| | | | - | - | 2500 | |
| Gate-emitter leakage current | I_{GES} | $V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$ | - | - | 100 | nA |
| Transconductance | g_{fs} | $V_{CE} = 20\text{V}, I_C = 20.0\text{A}$ | - | 14.8 | - | S |
| Integrated gate resistor | r_G | | | none | | Ω |

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|-------------------------------|-----------|---|-------|-------|------|---------------|
| | | | min. | typ. | max. | |
| Dynamic Characteristic | | | | | | |
| Input capacitance | C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | - | 1500 | - | μF |
| Output capacitance | C_{oes} | | - | 55 | - | |
| Reverse transfer capacitance | C_{res} | | - | 45 | - | |
| Gate charge | Q_G | $V_{CC} = 1080\text{V}, I_C = 20.0\text{A},$ $V_{GE} = 15\text{V}$ | - | 195.0 | - | nC |

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|---|--------------|--|-------|------|------|------|
| | | | min. | typ. | max. | |
| IGBT Characteristic, at $T_{vj} = 25^{\circ}\text{C}$ | | | | | | |
| Turn-off delay time | $t_{d(off)}$ | $T_{vj} = 25^{\circ}\text{C},$ $V_{CC} = 600\text{V}, I_C = 20.0\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(on)} = 15.0\Omega, R_{G(off)} = 15.0\Omega,$ $L_{\sigma} = 175\text{nH}, C_{\sigma} = 40\text{pF}$ L_{σ}, C_{σ} from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 335 | - | ns |
| Fall time | t_f | | - | 50 | - | ns |
| Turn-off energy | E_{off} | | - | 1.30 | - | mJ |

Resonant Switching Series

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|--|--------------|--|-------|------|------|------|
| | | | min. | typ. | max. | |
| IGBT Characteristic, at $T_{vj} = 175^{\circ}\text{C}$ | | | | | | |
| Turn-off delay time | $t_{d(off)}$ | $T_{vj} = 175^{\circ}\text{C}$, $V_{CC} = 600\text{V}$, $I_C = 20.0\text{A}$, $V_{GE} = 0.0/15.0\text{V}$, $R_{G(on)} = 15.0\Omega$, $R_{G(off)} = 15.0\Omega$, $L_{\sigma} = 175\text{nH}$, $C_{\sigma} = 40\text{pF}$ L_{σ} , C_{σ} from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 405 | - | ns |
| Fall time | t_f | | - | 100 | - | ns |
| Turn-off energy | E_{off} | | - | 2.25 | - | mJ |

Resonant Switching Series

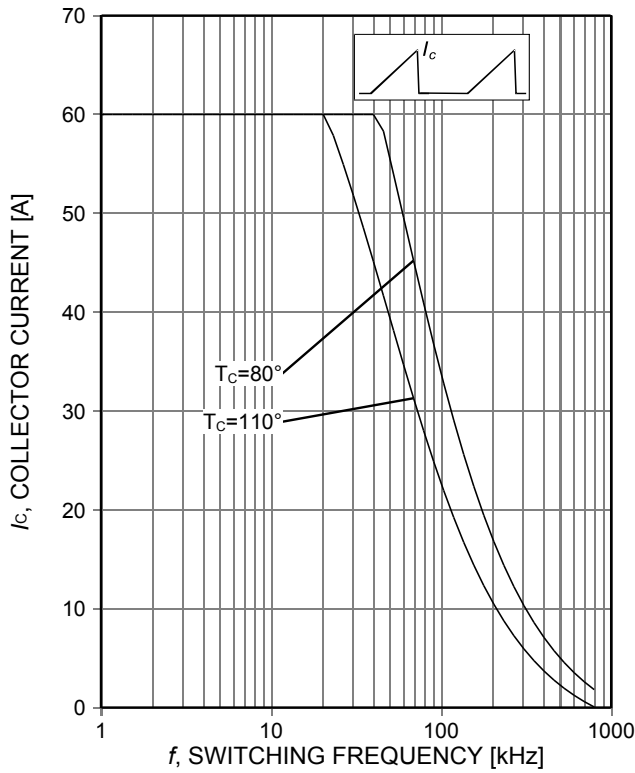


Figure 1. **Collector current as a function of switching frequency**
 ($T_{vj} \leq 175^\circ\text{C}$, $D=0.5$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=15\Omega$)

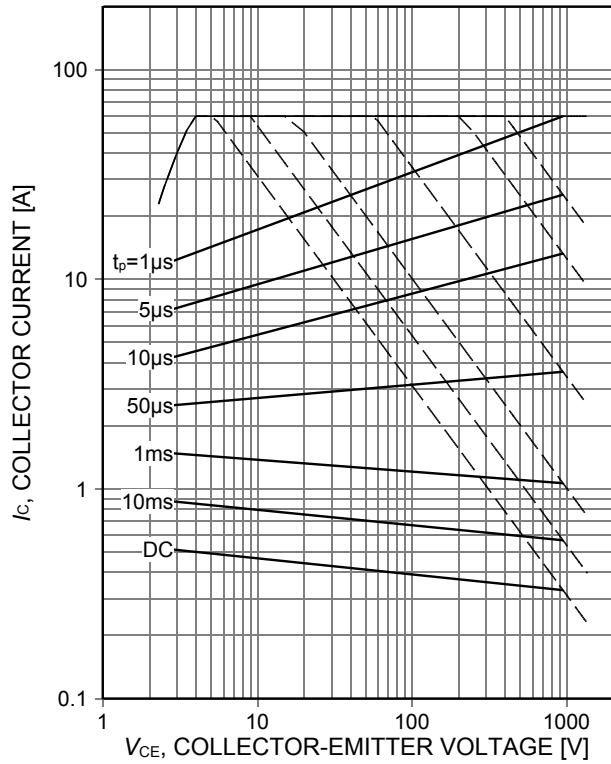


Figure 2. **Forward bias safe operating area**
 ($D=0$, $T_C=25^\circ\text{C}$, $T_{vj} \leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$)

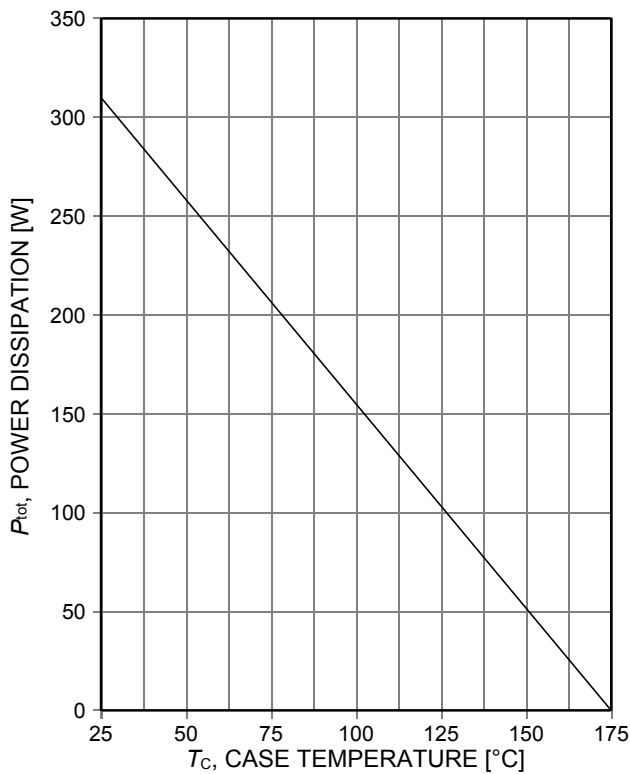


Figure 3. **Power dissipation as a function of case temperature**
 ($T_{vj} \leq 175^\circ\text{C}$)

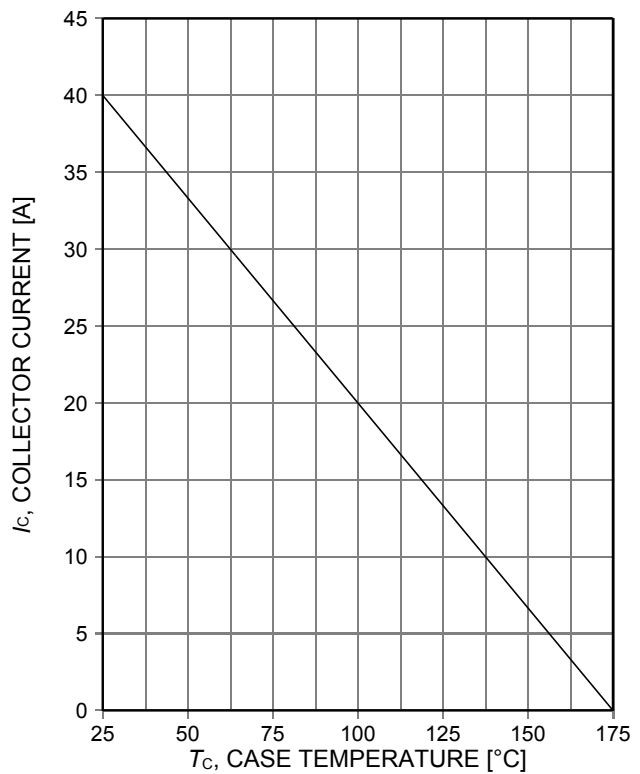


Figure 4. **Collector current as a function of case temperature**
 ($V_{GE} \geq 15\text{V}$, $T_{vj} \leq 175^\circ\text{C}$)

Resonant Switching Series

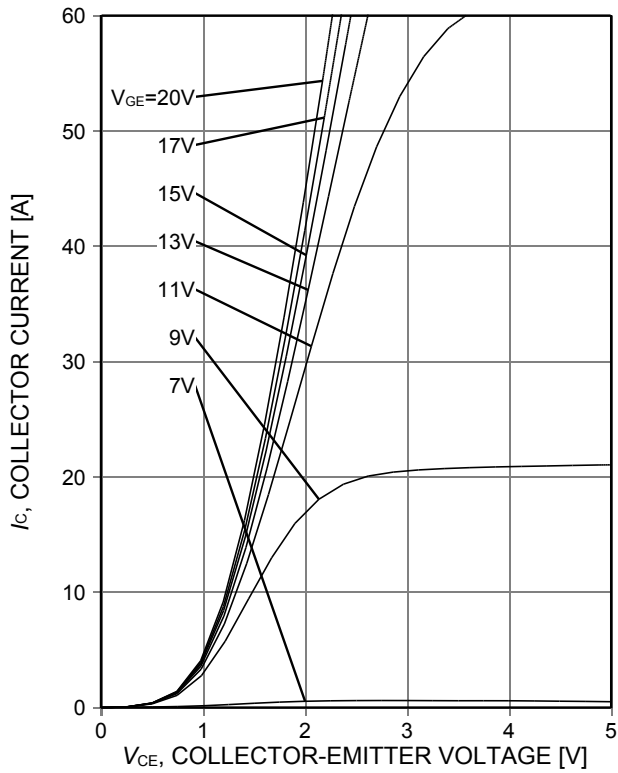


Figure 5. **Typical output characteristic**
($T_{vj}=25^{\circ}\text{C}$)

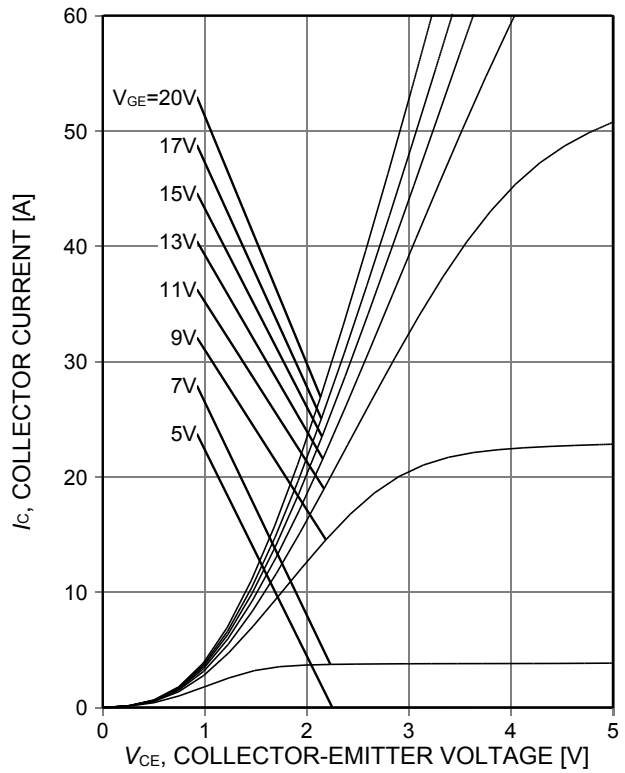


Figure 6. **Typical output characteristic**
($T_{vj}=175^{\circ}\text{C}$)

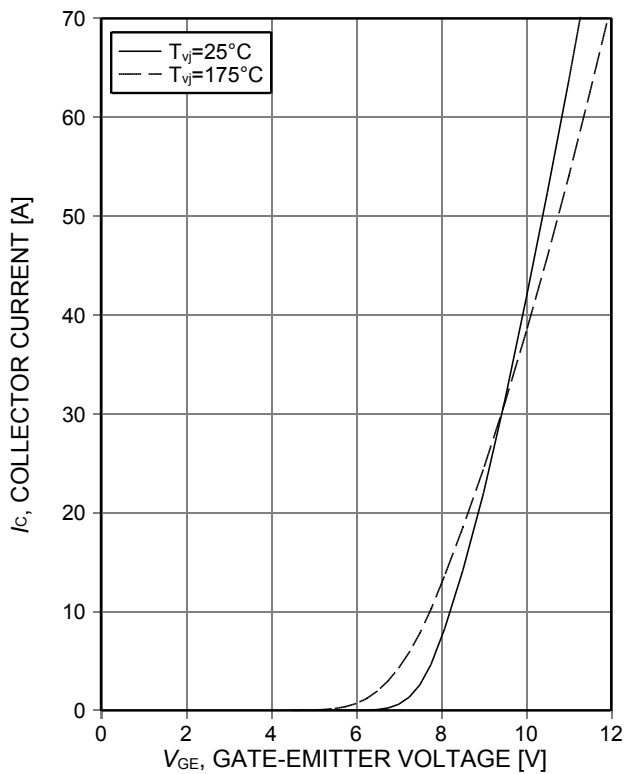


Figure 7. **Typical transfer characteristic**
($V_{ce}=20\text{V}$)

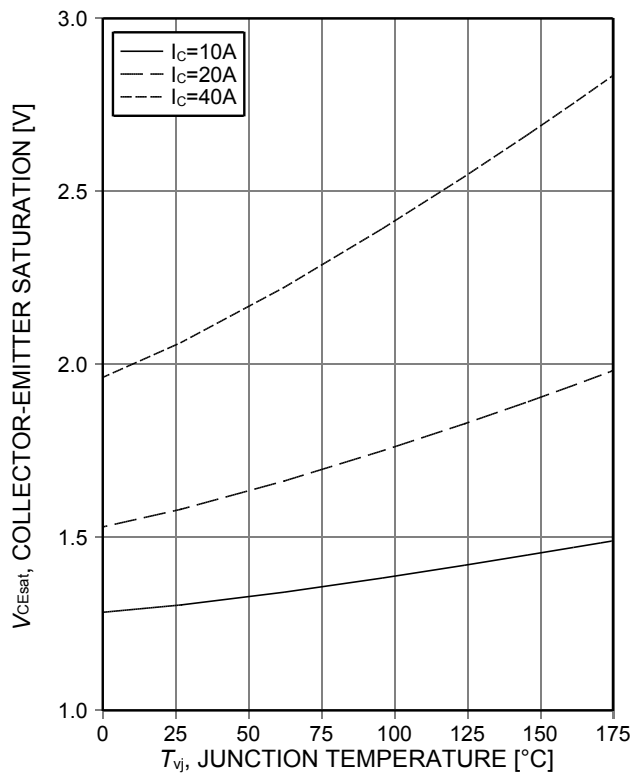


Figure 8. **Typical collector-emitter saturation voltage as a function of junction temperature**
($V_{ge}=15\text{V}$)

Resonant Switching Series

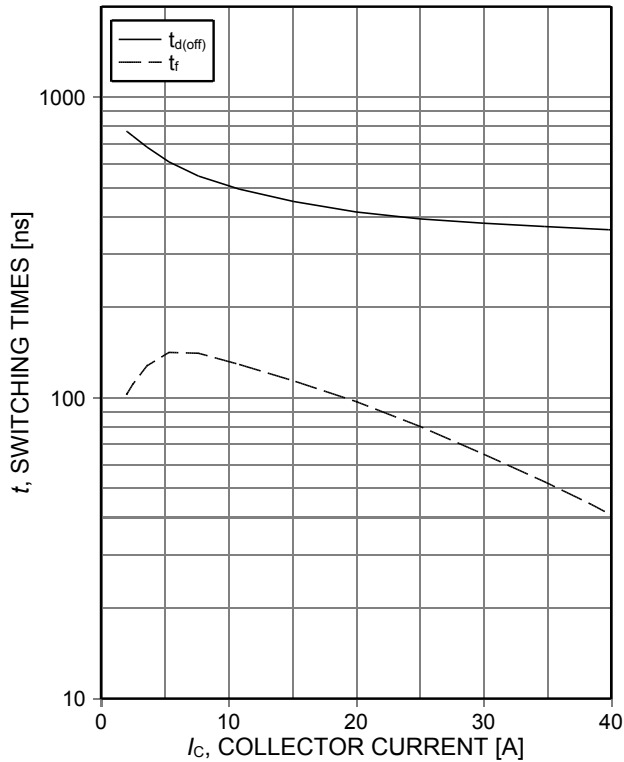


Figure 9. **Typical switching times as a function of collector current**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_{G(on)}=15\Omega$, $R_{G(off)}=15\Omega$, dynamic test circuit in Figure E)

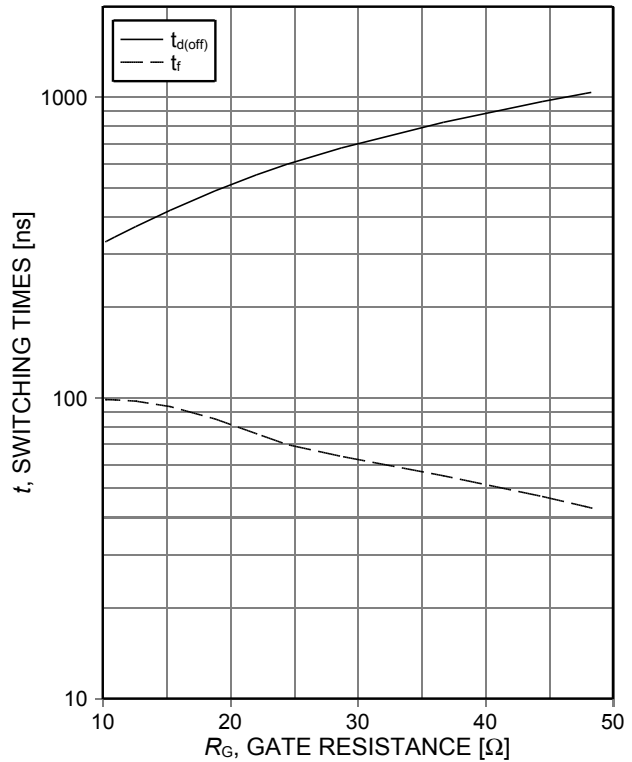


Figure 10. **Typical switching times as a function of gate resistance**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, dynamic test circuit in Figure E)

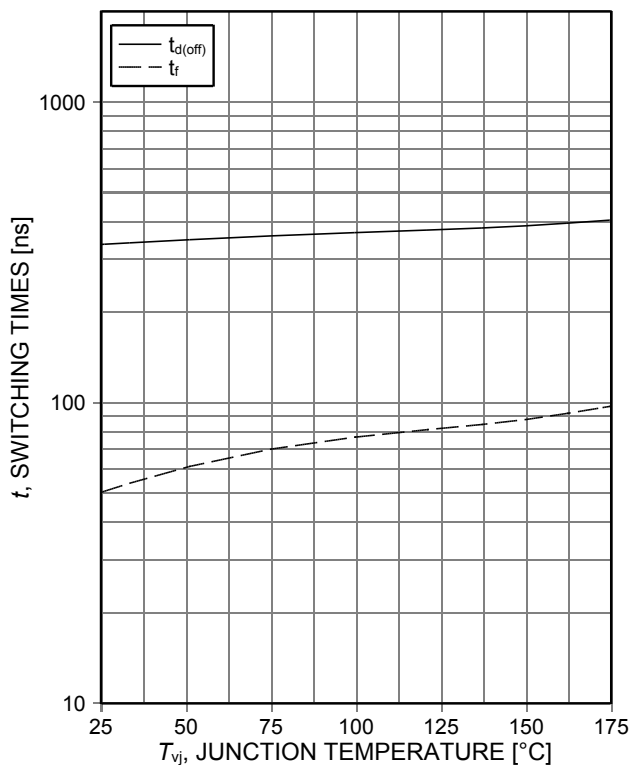


Figure 11. **Typical switching times as a function of junction temperature**
 (inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, $R_{G(on)}=15\Omega$, $R_{G(off)}=15\Omega$, dynamic test circuit in Figure E)

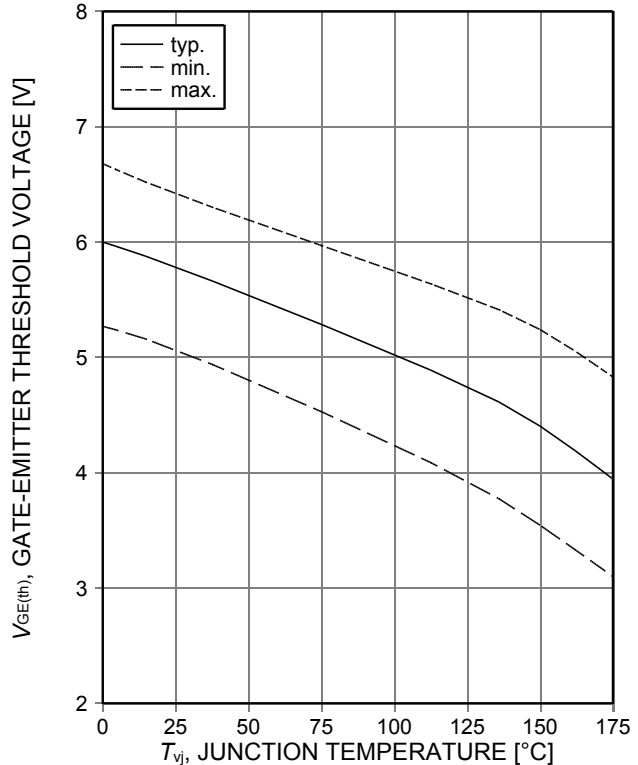


Figure 12. **Gate-emitter threshold voltage as a function of junction temperature**
 ($I_C=0.5\text{mA}$)

Resonant Switching Series

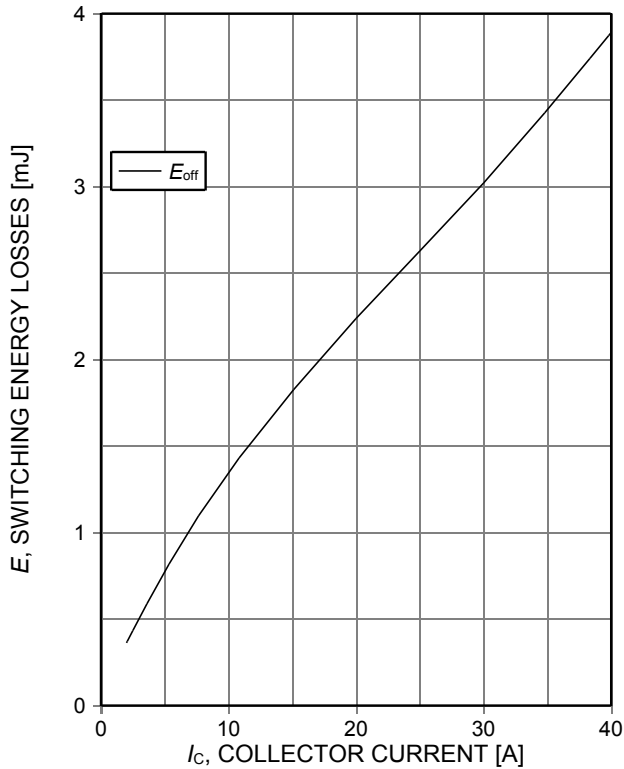


Figure 13. **Typical switching energy losses as a function of collector current**
 (inductive load, $T_{vj}=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_{G(on)}=15\Omega$, $R_{G(off)}=15\Omega$, dynamic test circuit in Figure E)

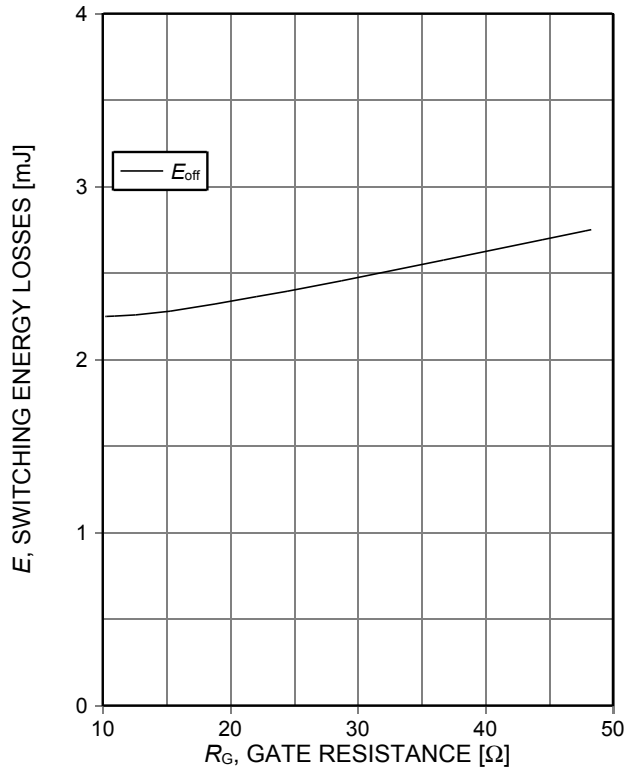


Figure 14. **Typical switching energy losses as a function of gate resistance**
 (inductive load, $T_{vj}=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, dynamic test circuit in Figure E)

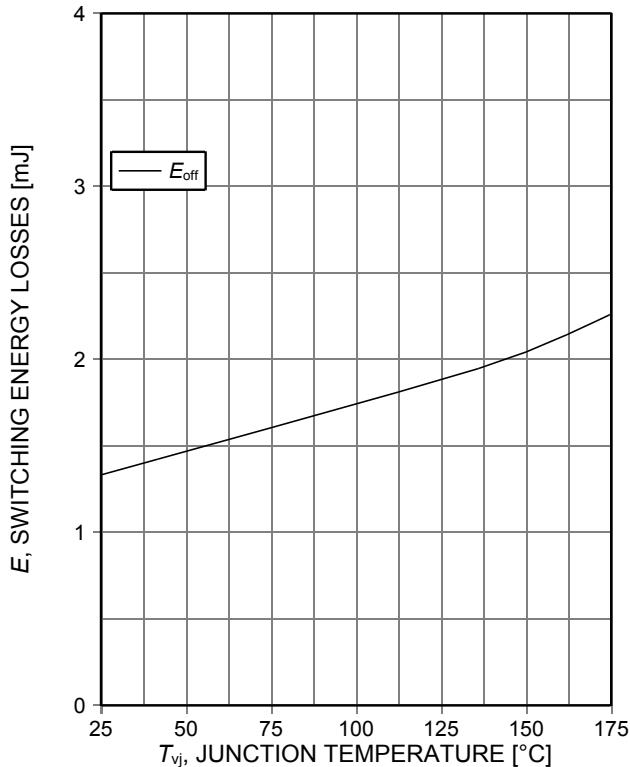


Figure 15. **Typical switching energy losses as a function of junction temperature**
 (inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, $R_{G(on)}=15\Omega$, $R_{G(off)}=15\Omega$, dynamic test circuit in Figure E)

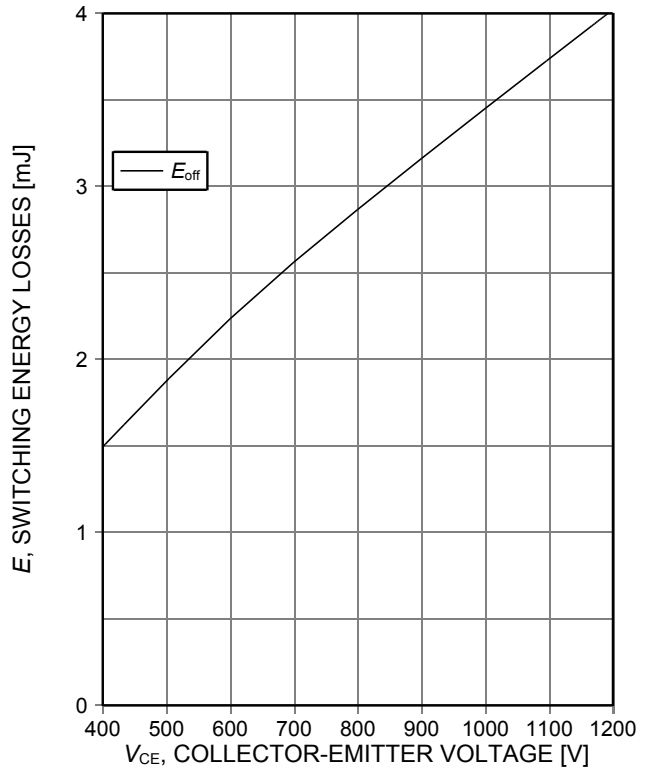


Figure 16. **Typical switching energy losses as a function of collector emitter voltage**
 (inductive load, $T_{vj}=175^\circ\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, $R_{G(on)}=15\Omega$, $R_{G(off)}=15\Omega$, dynamic test circuit in Figure E)

Resonant Switching Series

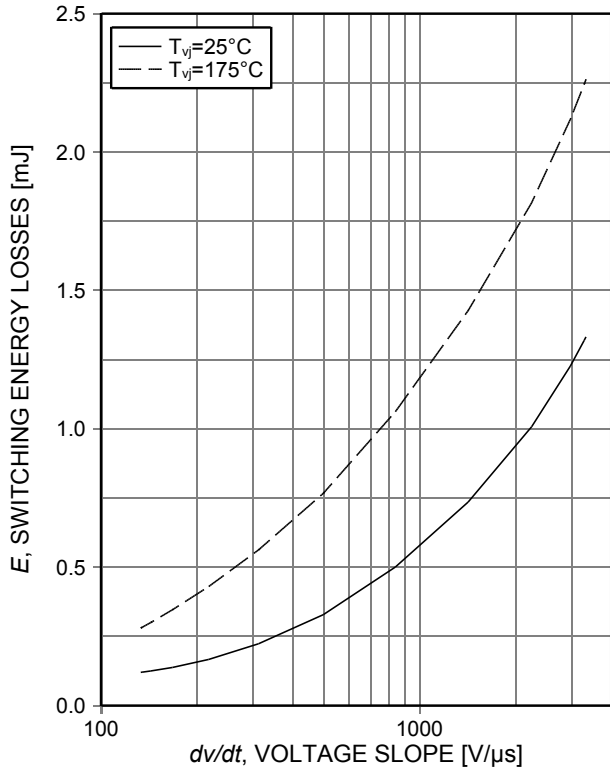


Figure 17. **Typical turn off switching energy loss for soft switching**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=20\text{A}$, $R_G=15\Omega$, dynamic test circuit in Figure E)

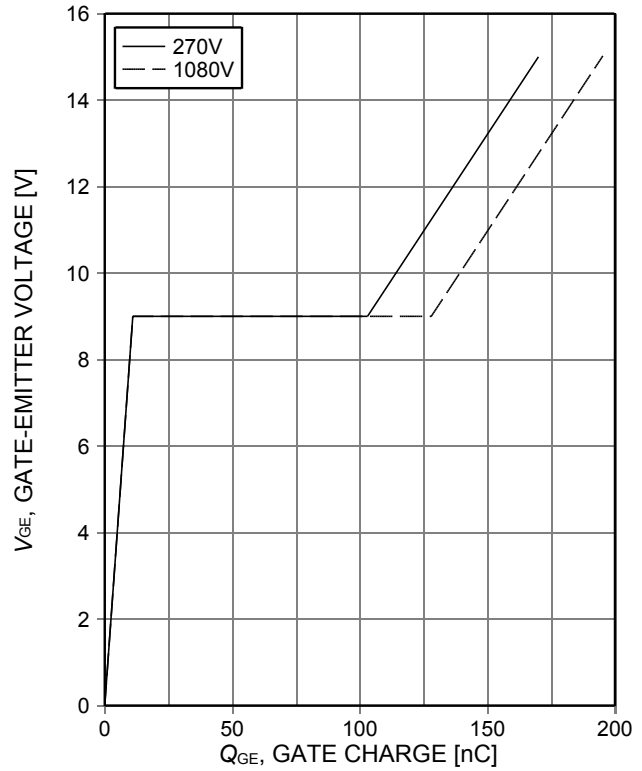


Figure 18. **Typical gate charge**
 ($I_C=20\text{A}$)

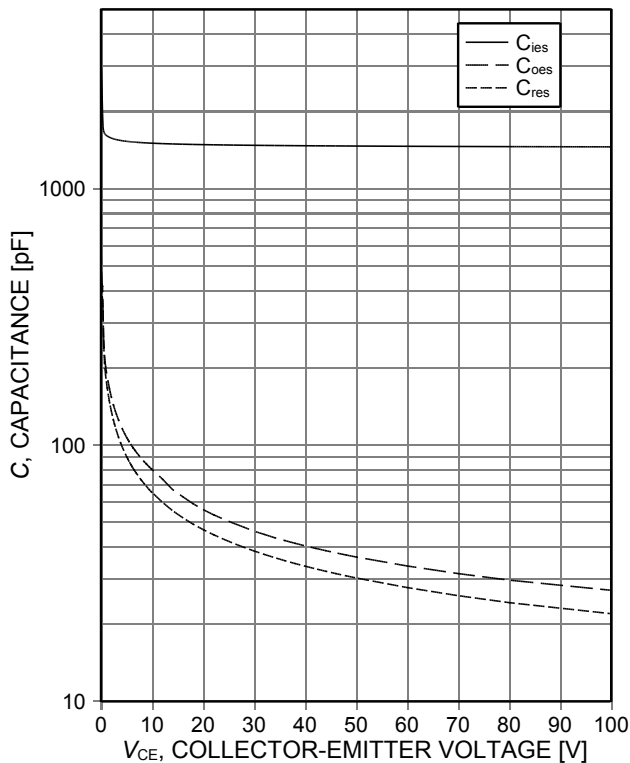


Figure 19. **Typical capacitance as a function of collector-emitter voltage**
 ($V_{GE}=0\text{V}$, $f=1\text{MHz}$)

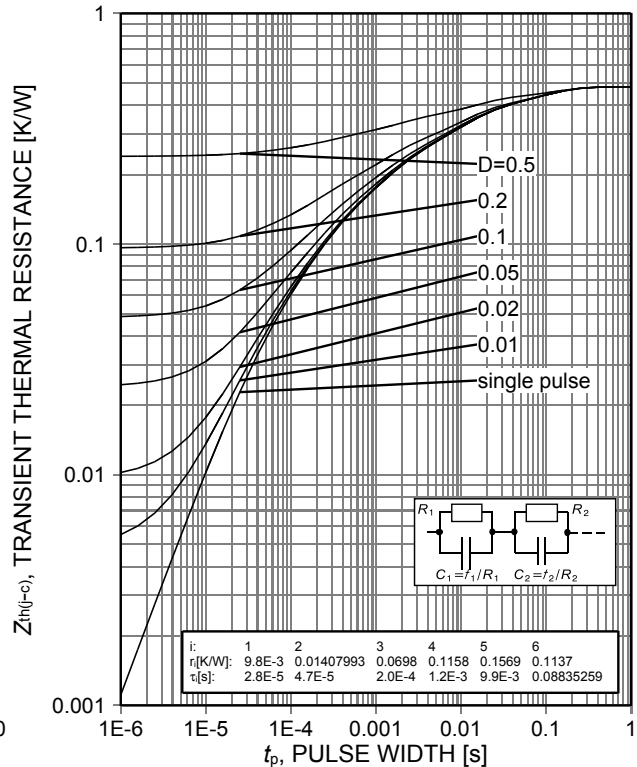


Figure 20. **IGBT transient thermal resistance**
 ($D=t_p/T$)

Resonant Switching Series

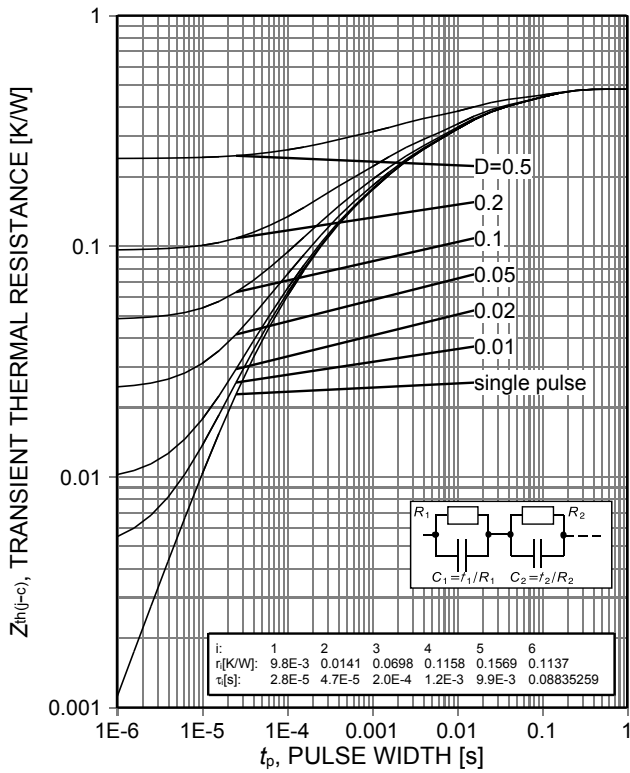


Figure 21. Diode transient thermal impedance as a function of pulse width ($D=t_p/T$)

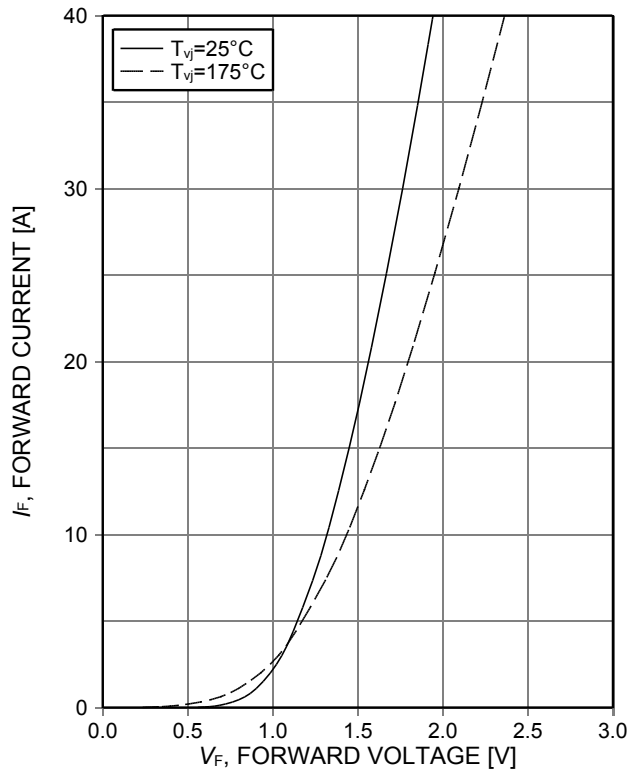


Figure 22. Typical diode forward current as a function of forward voltage

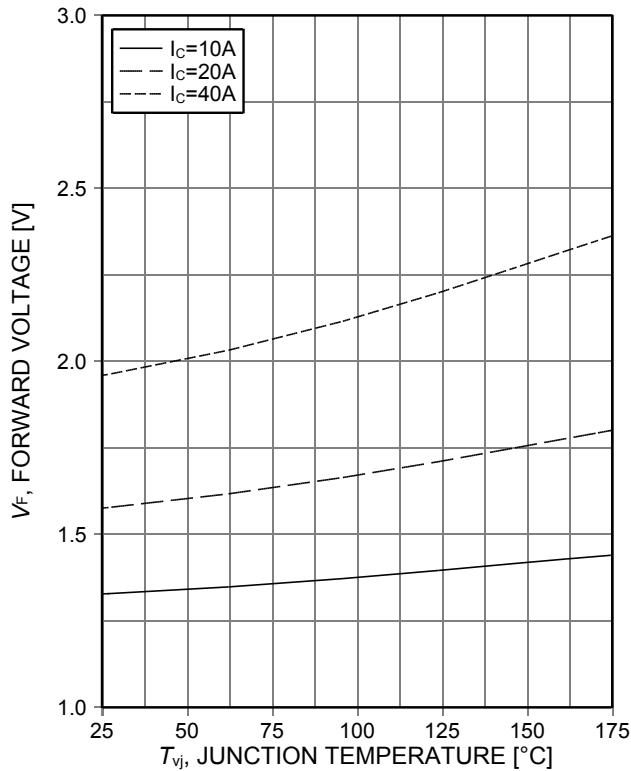
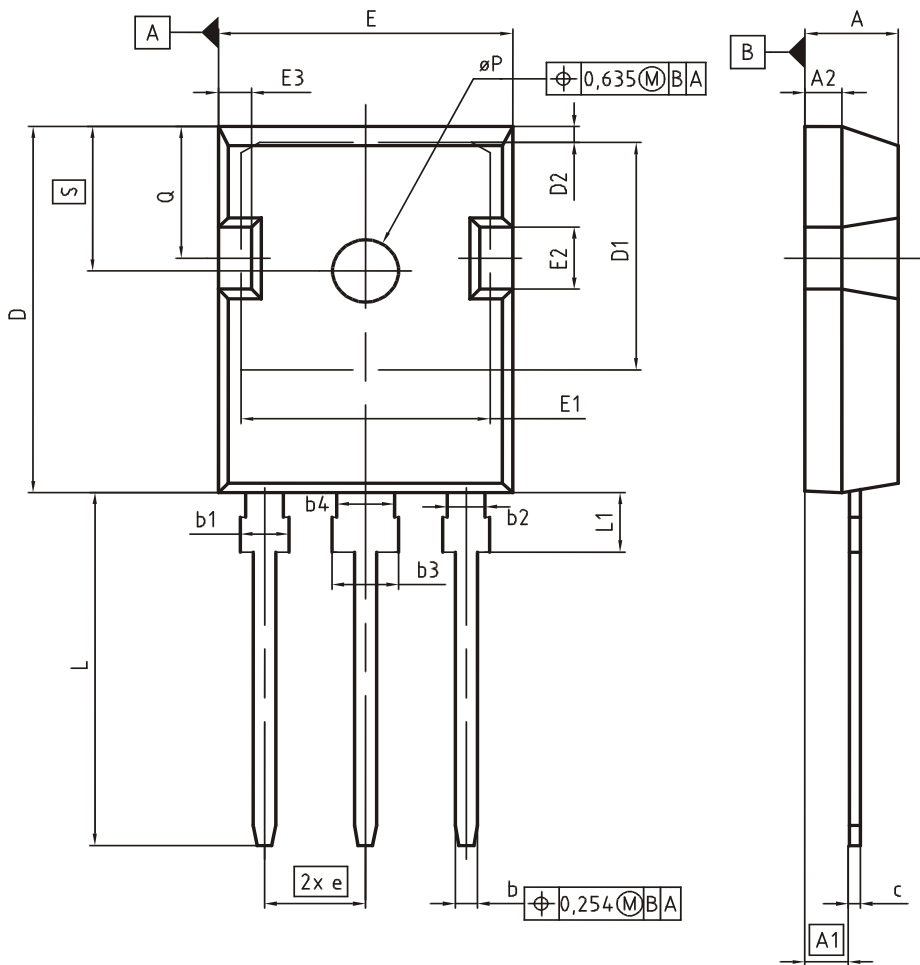


Figure 23. Typical diode forward voltage as a function of junction temperature

Package Drawing PG-TO247-3



| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.83 | 5.21 | 0.190 | 0.205 |
| A1 | 2.27 | 2.54 | 0.089 | 0.100 |
| A2 | 1.85 | 2.16 | 0.073 | 0.085 |
| b | 1.07 | 1.33 | 0.042 | 0.052 |
| b1 | 1.90 | 2.41 | 0.075 | 0.095 |
| b2 | 1.90 | 2.16 | 0.075 | 0.085 |
| b3 | 2.87 | 3.38 | 0.113 | 0.133 |
| b4 | 2.87 | 3.13 | 0.113 | 0.123 |
| c | 0.55 | 0.68 | 0.022 | 0.027 |
| D | 20.80 | 21.10 | 0.819 | 0.831 |
| D1 | 16.25 | 17.65 | 0.640 | 0.695 |
| D2 | 0.95 | 1.35 | 0.037 | 0.053 |
| E | 15.70 | 16.13 | 0.618 | 0.635 |
| E1 | 13.10 | 14.15 | 0.516 | 0.557 |
| E2 | 3.68 | 5.10 | 0.145 | 0.201 |
| E3 | 1.00 | 2.60 | 0.039 | 0.102 |
| e | 5.44 (BSC) | | 0.214 (BSC) | |
| N | 3 | | 3 | |
| L | 19.80 | 20.32 | 0.780 | 0.800 |
| L1 | 4.10 | 4.47 | 0.161 | 0.176 |
| øP | 3.50 | 3.70 | 0.138 | 0.146 |
| Q | 5.49 | 6.00 | 0.216 | 0.236 |
| S | 6.04 | 6.30 | 0.238 | 0.248 |

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SCALE

EUROPEAN PROJECTION

ISSUE DATE
09-07-2010

REVISION
05

Resonant Switching Series

Testing Conditions



Figure A. Definition of switching times

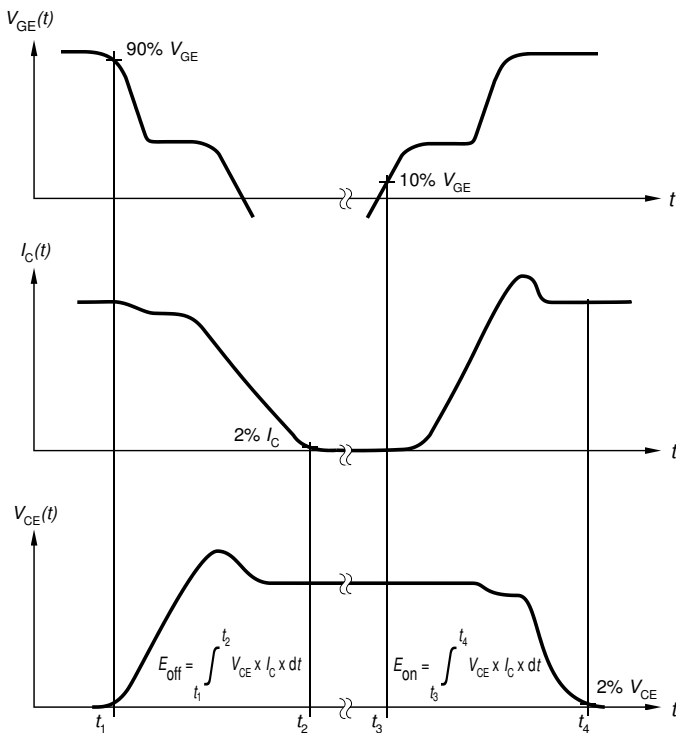


Figure B. Definition of switching losses



Figure C. Definition of diode switching characteristics



Figure D. Thermal equivalent circuit



Figure E. Dynamic test circuit
Parasitic inductance L_{σ} ,
parasitic capacitor C_{σ} ,
relief capacitor C_r ,
(only for ZVT switching)

Resonant Switching Series

Revision History

IHW20N135R3

Revision: 2018-03-29, Rev. 2.3

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.1 | 2011-05-03 | Final data sheet |
| 2.2 | 2015-01-26 | Minor changes |
| 2.3 | 2018-03-29 | Fig.12 and Fig.17 minor change of legend |

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9